



OLED SPECIFICATION

Model No:

REX012864FYPP3N00000

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

APPROVED BY	CHECKED BY	PREPARED BY
	1.00	
	APPROVED BY	APPROVED BY CHECKED BY

Release DATE:



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2013/08/28		First release
Α	2013/12/31		Update Rev.
В	2014/05/27		Update Block
			Diagram
С	2014/06/11		Correct Electrical
			Characteristics &
			Optical
			Characteristics
D	2014/06/16		Add Low Temperature
			storage.



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1.General Specification

The Features is described as follow:

■ Module dimension: 41.8× 27.9 × 1.8 mm

■ Active area: 36.45 × 18.21 mm

■ Dot Matrix: 128*64

Dot size: 0.255 × 0.255 mmDot pitch: 0.285 × 0.285mm

■ Display Mode : Passive Matrix

■ Duty: 1/64 Duty

■ Display Color: Yellow

■ IC: SSD1325



2.Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13
R	Е	Х	012864	F	Υ	Р	Р	3	N	0	0	000

Item	Description						
1	R : Raystar Optronics Inc.						
2	E: OLED						
3	Display Type: C→C	Character Type, G→Graphic Type,T→TAB Type ,X→COG Type					
4	Dot Matrix: 128*	64					
5	Serials code						
		A: Amber R: RED					
6	Emitting Color	B: Blue Y: Yellow					
		G : Green W : White					
7	Polarizer	P: With Polarizer; N: Without Polarizer					
8	Display Mode	P : Passive Matrix ; A: Active Matrix					
9	Driver Voltage	3: 3.0 V; 5: 5.0V					
10	Touch Panel	N: Without touch panel; T: With touch panel					
10	S : Resistive touch panel						
11	Species	0:Normal, 1:Sunlight readable, 2:Transparent, 3:Flexible,					
	·	4:Lighting					
12	Grade code						
13	Serial No.	Sales code					



3.Interface Pin Function

Pin No.	Symbol	Level	Description
1	NC(GND)		No Connection
			This is the most positive voltage supply pin of the chip. It can
2	VCC		be supplied externally or generated internally by using
			internal DC-DC voltage converter.
			This pin is the input pin for the voltage output high level for
3	VCOMH		COM signals. It can be supplied externally or internally.
3	VCOMIT		When VCOMH is generated internally, a capacitor should be
			connected between this pin and VSS.
			This pin is segment current reference pin. A resistor should
4	IREF		be connected between this pin and VSS. Set the current at
			10uA.
5	D7		
6	D6		
7	D5		These pins are 8-bit bi-directional data bus to be connected
8	D4		to the microprocessor's data bus. When serial mode is
9	D3		selected, D1 will be the serial data input SDIN and D0 will be
10	D2		the serial clock input SCLK.
11	D1		
12	D0		
			This pin is MCU interface input. When interfacing to a
		(6800-series microprocessor, this pin will be used as the
		1	Enable (E) signal. Read/write operation is initiated when this
13	E/RD#		pin is pulled high and the CS# is pulled low. When connecting
			to an 8080-microprocessor, this pin receives the Read (RD#)
			signal. Data read operation is initiated when this pin is pulled
			low and CS# is pulled low.



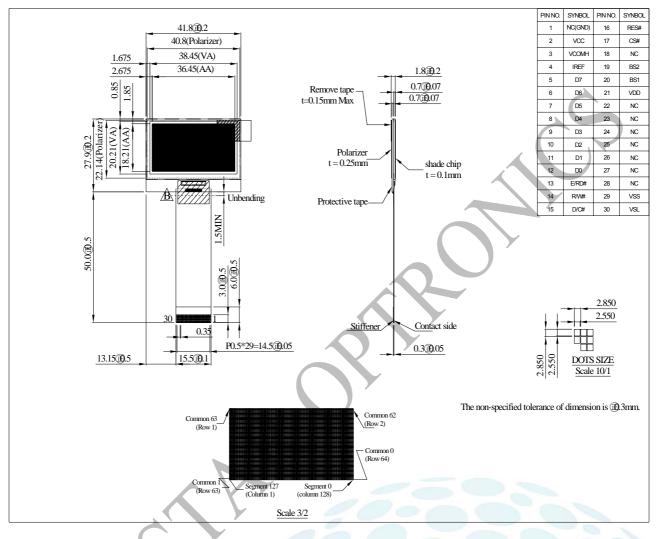
			This pir	n is MCU inter	face input. W	hen interf	acing to a			
				eries micropro	•		•			
			Read/Write (R/W#) selection input. Pull this pin to "High" for							
14	R/W#		read mode and pull it to "LOW" for write mode. When 8080							
			interface mode is selected, this pin will be the Write (Wi							
					•					
			input. Data write operation is initiated when this pin is pull low and the CS# is pulled low.							
				'		nin Whe	n the pin is pulled			
							y data. When the			
15	D/C#			•			ransferred to the			
10	D/Oπ						MCU interface			
				· ·		, ,	ristics Diagrams.			
							s low, initialization			
16	RES#					i tile pili i	S low, illitialization			
			of the chip is executed. This pin is the chip select input. The chip is enabled for MCU							
17	CS#				J	-				
40	NO			nication only	When CS# is	pulled low	<i>1</i> .			
18	NC			nection						
				oins are MCU	interface sele	ection inpi	ut. See the			
19	BS2		followin	,-						
			MCU in	terface setting						
				6800-parallel interface	8080-parallel interface	Serial interface	75%			
			BS0	0	0	0	000			
20	BS1		BS1 BS2	0	1	0	0			
		Y	D32	1	'	10				
21	VDD		This is	a voltage supp	oly pin. It mus	t be conn	ected to external			
21	VDD	1	source.							
22	NC		No Connection							
23	NC		No Con	No Connection						
24	NC		No Con	No Connection						
25	NC		No Con	nection		1000				
	l	l				11000				



26	NC	No Connection
27	NC	No Connection
28	NC	No Connection
29	VSS	This is a ground pin. It also acts as a reference for the logic pins and the OLED driving voltages. It must be connected to external ground.
30	VSL	This pin is the output pin for the voltage output low level for SEG signals. A capacitor should be connected between this pin and VSS

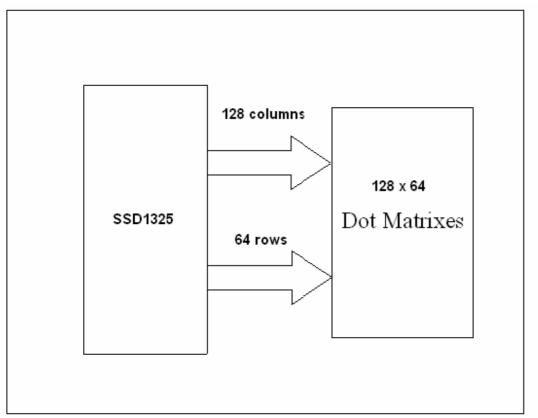


4. Counter Drawing & Block Diagram





FUNCTION BLOCK DIAGRAM



^{*}For more information, please refer to Application Note provided by Raystar Optronics.



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5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1, 2
Supply Voltage for Display	VCC	0	15	V	1, 2
Operating Temperature	TOP	-40	+80	°C	<u> </u>
Storage Temperature	TSTG	-40	+80	°C	, -

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate

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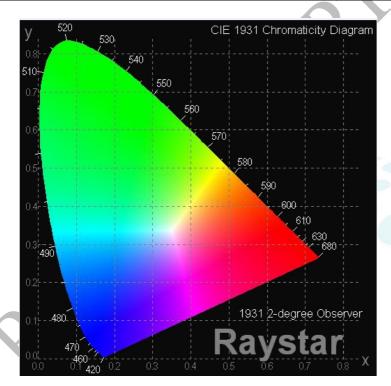
6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	3.0	3.3	3.5	V
Supply Voltage for Display	VCC	_	10	12	15	\
High Level Input	VIH	_	0.8×V _{DD}	_	V_{DD}	\
Low Level Input	VIL	_	0	- 4	0.2×V _{DD}	V
High Level Output	VOH	_	0.9×V _{DD}	1	V_{DD}	V
Low Level Output	VOL	_	0	7	$0.1 \times V_{DD}$	V
50% Check Board operating Current	ICC	VCC =12 V	10	12	15	mA



7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	_	160	_		deg
View / uigie	(Η)φ	_	160	_	7	deg
Contrast Ratio	CR	Dark	2000:1	え	-)`	
Response Time	T rise	_		10	<i>y</i>	μs
	T fall	_	-	10	_	μs
Display with 50% check	90	110	_	cd/m2		
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	_
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	_





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8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°ℂ / Initial 50% check Board Typical Brightness Value	80,000 Hrs	100,000 Hrs	Note

Note:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.





9.Reliability

Content of Reliability Test

Environmental Test				
Test Item	Content of Test	Test Condition	Applicable Standard	
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°ℂ 240hrs	- (
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40℃ 240hrs		
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs		
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40℃ 240hrs	_	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60℃,90%RH 240hrs		
Endurance test applying the low and high temperature cycle. Temperature Cycle 30min 5min 30min		-40°C/80°C 100 cycles		
Mechanical Tes	1 cycle			
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	30	
Constructional and mechanical shock test endurance test applying the shock during transportation.		50G Half sin wave 11 ms 3 times of each direction	-56	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs		
Others				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	10000	



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

NO	Item	Criterion			AQL
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect.			
		1.2 Missing character , dot or icon.			
		1.3 Display malfunction.			
		1.4 No function or no disp	•	acifications	0.65
		1.5 Current consumption exceeds product specifications.1.6 OLED viewing angle defect.			
		1.7 Mixed product types.	.0.000.		
		1.8 Contrast defect.			
00	DI I	0.4 \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	l' 1 <0.05		
02	Black or white	2.1 White and black spots three white or black spots		nm, no more than	
	spots on	2.2 Densely spaced: No n		or lines within	
	OLED	3mm.			2.5
	(display				
03	only) OLED	2.1 Dound type : As			
03	black	3.1 Round type : As following drawing	SIZE	Acceptable Q	
	spots,	$\Phi = (x + y) / 2$		TY	
	white	X	Ф≦0.10	Accept no	
	spots,	→	0.40	dense	2.5
	contamina tion	- Y 0.10<		2	2.5
	(non-displ	_T	Φ≦0.20 0.20<	1	
	ay)		0.20 Φ≦0.25		
		X ' ' '	Ф <u>=</u> 0.25<Ф	0	
		3.2 Line type : (As following drawing)		0,	
		Length	Width	Acceptable Q TY	
			W≦0.02	Accept no dense	
		→ L≦3.0	0.02 <w≦0.03< td=""><td>2</td><td>2.5</td></w≦0.03<>	2	2.5
		L≦2.5	0.03 <w≦0.05< td=""><td>-</td><td></td></w≦0.05<>	-	
		V	0.05 <w< td=""><td>As round type</td><td></td></w<>	As round type	
04	Polarizer				
	bubbles	If bubbles are visible,	Size Φ	Acceptable Q TY	
	7	judge using black spot specifications, not easy	Φ≦0.20	Accept no dense	
		to find must check in		3	2.5
		specify direction.	0.50<Φ≦1.00	2	000
			1.00 < Φ Total Q TY	0	
			IUIAI Q I I	3	



NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination	
		Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length:	
		6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:	
06	Chipped glass	z: Chip thickness y: Chip width x: Chip length Z≤1/2t Not over viewing area x≤1/8a	2.5
	giard		
		6.1.2 Corner crack:	
		X	
		z: Chip thickness y: Chip width x: Chip length	
		Z≤1/2tNot over viewing areax≤1/8a	
		1/2t $<$ z \leq 2t Not exceed 1/3k $x \leq$ 1/8a	
⊙ If there are 2 or more chips, x is the total length of each chip.			



Symbols : x: Chip length y: Chip width z: Chip thickness	
v: Chin length v: Chin width z: Chin thickness	
k: Seal width t: Glass thickness a: OLED side length	
L: Electrode pad length	
6.2 Protrusion over terminal :	
6.2.1 Chip on electrode pad :	
y: Chip width x: Chip length z: Chip thickness	
$y \le 0.5$ mm $x \le 1/8$ a $0 < z \le t$	
6.2.2 Non-conductive portion:	
0.2.2 Non conductive pertion.	
06 Glass	2.5
crack Z	2.3
X	
y: Chip width x: Chip length z: Chip	
y. Only width (x. Only length (2. Only thickness)	
$y \le L$ $x \le 1/8a$ $0 < z \le t$	
⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO	
must remain and be inspected according to electrode terminal	5
specifications.	16
⊙ If the product will be heat sealed by the customer, the alignment	
mark not be damaged.	
6.2.3 Substrate protuberance and internal crack.	
y: width x: length	
y width x. ichight y ≤ 1/3L x ≤ a	
y y y	
	23-
	- 0



NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65



12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	NO	Item	Criterion	AQL
	12		 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to 	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65



Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel



11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time...
- (10) Raystar has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

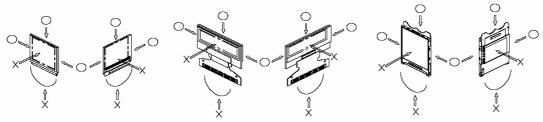
11.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.





- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Raystar Optronics Inc. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.



11.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.



Page: 1			
Module Sample Estimate Feedback Sheet			
Module Number:			
1 - Panel Specification :			
1. Panel Type:	□ Pass	□NG ,	
2. Numbers of Pixel:	□ Pass	□NG ,	
3. View Area:	□ Pass	□NG ,	
4. Active Area:	□ Pass	□NG ,	
5.Emitting Color:	□ Pass	□NG ,	
6.Uniformity:	□Pass	□NG ,	
7.Operating	□ Pass	□NG ,	
Temperature :		y	
8.Storage Temperature :	□ Pass	□NG ,	
9.Others :			
2 · Mechanical Specification	<u>on</u> :	A Y	
1. PCB Size :	□Pass	□NG ,	
2.Frame Size :	□Pass	□NG ,	
3.Materal of Frame:	□Pass	□NG ,	
4.Connector Position:	□Pass	□NG ,	
5.Fix Hole Position:	□Pass	□NG ,	
6. Thickness of PCB:	□Pass	□NG ,	
7. Height of Frame to	□Pass	□NG ,	
PCB:	` Y. *		
8.Height of Module:	□Pass	□NG ,	
9.Others:	□Pass	□NG ,	
3 · Relative Hole Size :			
1.Pitch of Connector:	□Pass	□NG ,	
2.Hole size of	□Pass	□NG ,	
Connector:			
3.Mounting Hole size :	□Pass	□NG ,	
4.Mounting Hole Type:	□Pass	□NG ,	
5.Others:	□Pass	□NG .	

>> Go to page 2 <<



Page: 2

Module Number :				
4 · Electronic Characteristics of Module :				
1.Input Voltage :	□Pass	□NG ,		
2.Supply Current:	□Pass	□NG ,		
3.Driving Voltage for OLED:	□Pass	□NG ,		
4.Contrast for OLED:	□Pass	□NG ,		
5.Negative Voltage	□Pass	□NG ,		
Output:				
6.Interface Function:	□Pass	□NG ,		
7.ESD test:	□Pass	□NG ,		
8.Others:	□Pass	□NG ,		
5 · Summary :				
Sales signature : Customer Signature	•			
oustomer signature				

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

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Other Similar products are found below:

LTC-2721WC LTC-4624JD LTC-4627G LTC-4627WC LTD-5021AWC LTM-8522G LTP-4323P LTP-747G LTS-3361JG-06

F416SYGWA/S530-E3 EADST040RA2 1668 HT-F196NB-5323 IPD2131-27 SA03-12EWA LDD-E2802RD LDD-E306MI LDQ-N514RI

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LTC-2623WC LTC-4624P LTC-4627JD LTD-2601E LTD-322G LTD-482PC LTP-1457AKR LTP-3784G-01 LTS-313AP LTS-4812SKR-P LTS-547AE LTS-6780P 446010401-3 HV-7W30-6829 CA12240_MINNIE-WWW-MTG-ASSY DA43-11GWA LDD-A516RI-17 LDD-E305RI LDQ-M513RI LDQ-M5204RI-SI LDQ-N3402RI LDQ-N3606RI LDS-A3924RI-SI